

# COOLTHERM® SC-6709 SILICONE RESIN

## Technical Data Sheet

CoolTherm® SC-6709 silicone resin is formulated for use with various CoolTherm and Circalok™ hardeners to create a two-component, solvent-free RTV silicone system. The silicone system is an ideal potting compound for any application where rapid heat transfer, high temperature service and a flexible system are required.

CoolTherm SC-6709 resin can be catalyzed with CoolTherm SC-6731, CoolTherm SC-6730, or Circalok 6732 hardener. CoolTherm SC-6730 hardener is blue-green in color and assures thorough mixing by visual examination.

### Features and Benefits

**Low Viscosity:** maintains low viscosity for complete and void-free encapsulation.

**High Thermal Conductivity:** provides thermal conductivity for applications where superior heat dissipation are required.

**Low Coefficient of Thermal Expansion:** minimizes the possibility of cracking during severe temperature cycling.

**Broad Temperature Range:** can be used on parts and devices that experience operating temperatures from -68°C to +205°C.

### Application

**Mixing:** Thoroughly stir CoolTherm SC-6709 resin within its shipping container to ensure uniform dispersion. Transfer amount of resin needed to a clean container and add proper amount of hardener by weight.

Thoroughly mix silicone system to ensure catalyzation.

**Applying:** Apply material using automatic meter/mix/dispense equipment.

**Curing:** Cure time will vary depending on hardener used. Refer to cure schedule indicated. This time-at-temperature profile refers to the time the material should be allowed to cure once it reaches the target temperature. Allowance should be made for oven ramp rates, parts with large thermal mass and other circumstances that may delay material reaching the target temperature.

### Shelf Life/Storage

Shelf life is six months when stored at 25°C in original, unopened container.

### Typical Properties\*

Appearance	White Liquid
Viscosity, cP @ 25°C	32,000
Specific Gravity @ 25°C	1.80

\*Data is typical and not to be used for specification purposes.

### Typical Properties\* of Resin Mixed with Hardener

	CoolTherm SC-6731 Hardener	CoolTherm SC-6730 Hardener		Circalok 6732 Hardener
Mix Ratio, Resin to Hardener by Weight	100:0.5	100:5	100:10	100:0.5
Gel Time, hours @ 25°C	1 - 2	0.5 - 1	0.5 - 1	2 - 3
Cure Time, hours @ 25°C	12 - 16	8 - 12	8 - 12	6 - 8

\*Data is typical and not to be used for specification purposes.

## Typical Cured Properties\*\*

Thermal Conductivity, W/m-K Hot Disc Transient Method, ISO 22007-2	1.0
Coefficient of Linear Thermal Expansion, ppm/°C	50
Hardness Shore A	50
Tensile Strength, MPa (psi) @ 25°C	2.14 (310)
Elongation at Break, %	115
Moisture Absorption, % 10 days @ 25°C	0.08
Volume Resistivity, ohm-cm @ 25°C	1 x 10 <sup>5</sup>
Dielectric Strength, kV/mm (V/mil) ASTM D 149	21.7 (550)
Dielectric Constant @ 25°C ASTM D 150	5.1
Dissipation Factor @ 25°C ASTM D 150	0.02

\*\*Data is typical and not to be used for specification purposes.  
Cured properties are the same regardless of the hardener used.

## Cautionary Information

Before using this or any Parker Lord product, refer to the Safety Data Sheet (SDS) and label for safe use and handling instructions.

Verify Volatile Organic Compounds (VOC) requirements with the applicable local, regional and state air quality authorities before importing, selling or using this product. VOC rules, thresholds and reporting obligations vary by jurisdiction; compliance is the responsibility of the importer/seller/owner.

*For industrial/commercial use only.* Must be applied by trained personnel only. Not to be used in household applications. Not for consumer use.

Parker Lord  
**Engineered Materials Group**  
111 LORD Drive  
Cary, NC 27511-7923  
USA  
phone +1 877 275-5673  
[www.parker.com/APS](http://www.parker.com/APS)

DS3570 OD 01/26 Rev.4

Information and specifications subject to change without notice and without liability therefor.  
Trademarks used herein are the property of their respective owners.

© 2026 Parker Hannifin Corporation



Values stated in this document represent typical values as not all tests are run on each lot of material produced. For formalized product specifications for specific product end uses, contact the Customer Support Center.

Information provided herein is based upon tests believed to be reliable. In as much as Parker Lord has no control over the manner in which others may use this information, it does not guarantee the results to be obtained. In addition, Parker Lord does not guarantee the performance of the product or the results obtained from the use of the product or this information where the product has been repackaged by any third party, including but not limited to any product end-user. Nor does the company make any express or implied warranty of merchantability or fitness for a particular purpose concerning the effects or results of such use.

**WARNING — USER RESPONSIBILITY. FAILURE OR IMPROPER SELECTION OR IMPROPER USE OF THE PRODUCTS DESCRIBED HEREIN OR RELATED ITEMS CAN CAUSE DEATH, PERSONAL INJURY AND PROPERTY DAMAGE.**

This document and other information from Parker-Hannifin Corporation, its subsidiaries and authorized distributors provide product or system options for further investigation by users having technical expertise.

The user, through its own analysis and testing, is solely responsible for making the final selection of the system and components and assuring that all performance, endurance, maintenance, safety and warning requirements of the application are met. The user must analyze all aspects of the application, follow applicable industry standards, and follow the information concerning the product in the current product catalog and in any other materials provided from Parker or its subsidiaries or authorized distributors.

To the extent that Parker or its subsidiaries or authorized distributors provide component or system options based upon data or specifications provided by the user, the user is responsible for determining that such data and specifications are suitable and sufficient for all applications and reasonably foreseeable uses of the components or systems.